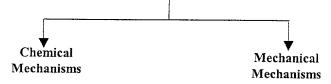
Laser Assisted Particle Removal



- Photochemical reactive removal
- Photo- + thermochemical reactive removal

- Particle deformation
- Substrate deformation
- Energy transfer medium explosive evaporation

Fig. 1

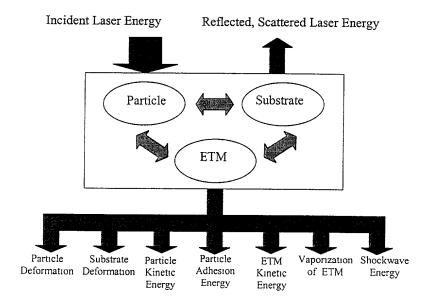


Fig. 2

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Absorption Medium	Particle	ETM	Substrate with ETM	Substrate without ETM
Removal Mechanism	Rapid thermal expansion of particle	Explosive evaporation of ETM	Microbubble formation at liquid/solid interface	Rapid thermal expansion of the substrate
wavelength	λ< <particle diameter<="" td=""><td>λ>>Particle Diameter</td><td>λ>Particle Diameter</td><td>λ>>Particle Diameter or λ<particle <math="" diameter="" if="">\alpha_{particle} is low</particle></td></particle>	λ>>Particle Diameter	λ>Particle Diameter	λ >>Particle Diameter or λ <particle <math="" diameter="" if="">\alpha_{particle} is low</particle>
Energy Absorption	$\alpha_{\text{particle}} >> \alpha_{\text{substrate}}$	High α _{ΕΤΜ}	High α _{substrate}	High $lpha_{ extsf{suostrate}}$
Substrate Damage	-Melting/Ablation of particle	Shockwave, substrate absorption	-Melting/Ablation of particle or substrate -Shockwave in ETM	Melting/Ablation of particle or substrate
Particle Removal Threshold	$Φ_h$ =0.01-0.08 J/cm ² I_h =1-11 MW/cm ² D=20 μm	Φ _{th} =0.65-2.2 J/cm ² I _{th} =3-11 MW/cm ²	θ_{th} =0.02-0.3 J/cm ² l_{th} =2-600 MW/cm ² τ =0.03-20 ns	Φ_{th} =0.02-0.3 J/cm ² l_{th} =1-30 MW/cm ² τ =7-30 ns

Fig. 3

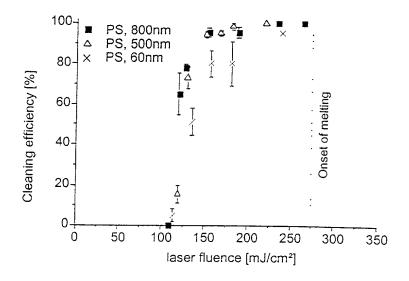


Fig. 4

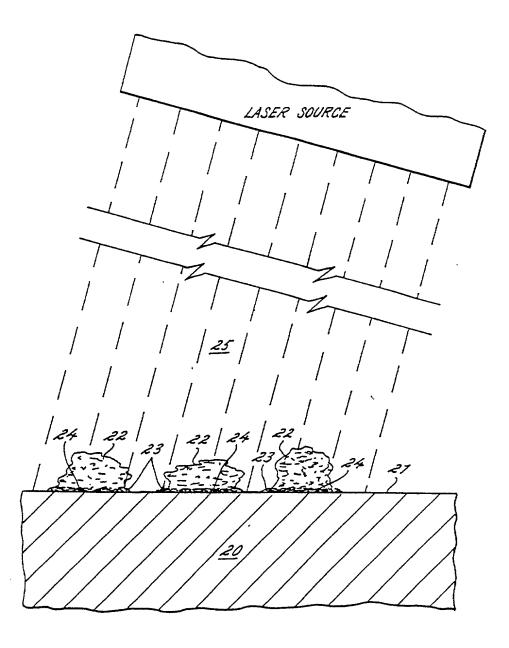
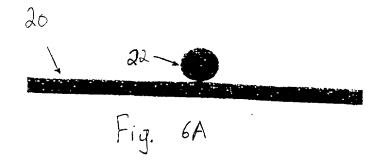
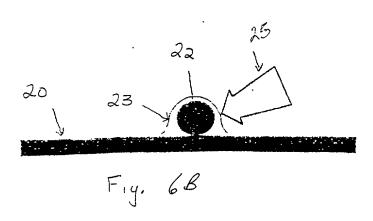
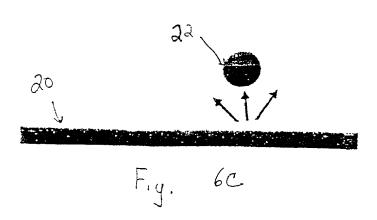


FIG. 5







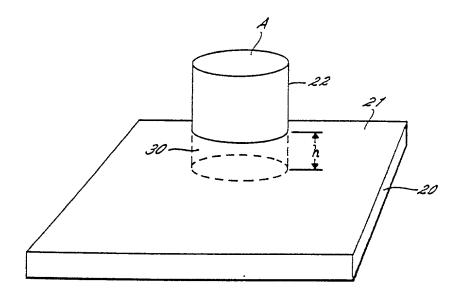
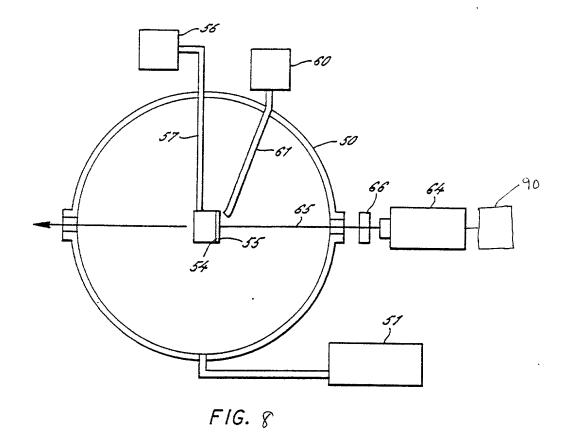


FIG. 7



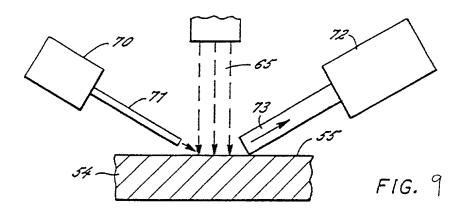
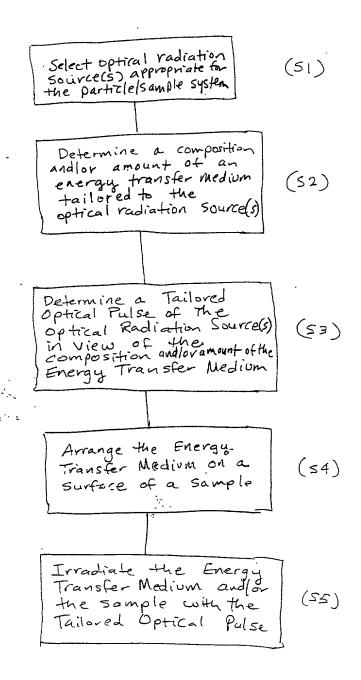


Figure 10



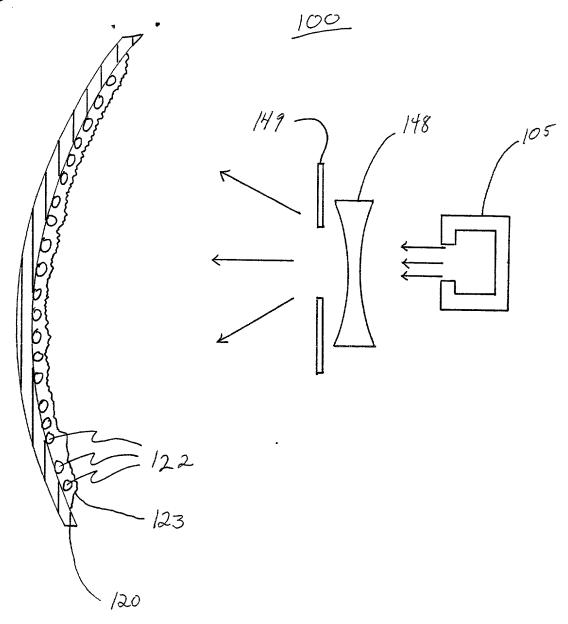


Fig. 11

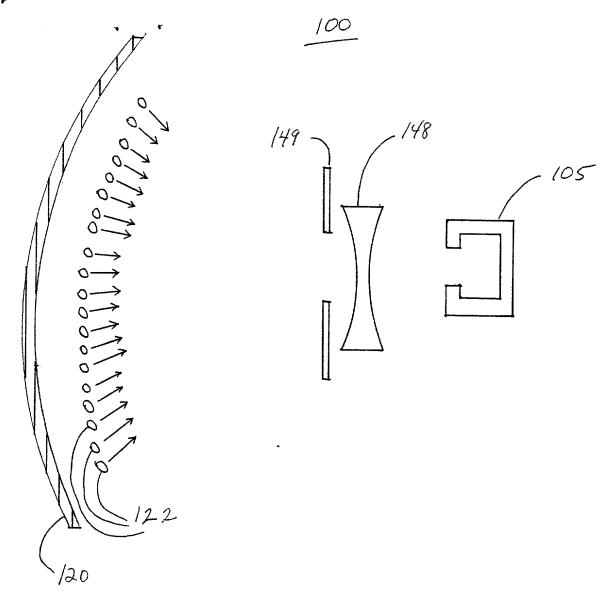


Fig 12

Fig 13